

IN THE CLAIMS

Please cancel Claims 1, 2, 13, and 16 without prejudice or disclaimer.

Claims 1 and 2 (cancelled)

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Claim 3 (currently amended): A wafer transfer machine for transferring wafers from either of a first wafer cassette and a second wafer cassette having incompatible registration features into the other, comprising:

(a) a support plate having a top surface for supporting the first and second wafer cassettes;

(b) a first registration boss attached to the top surface for extending upward into and engaging a first registration feature of the first wafer cassette, and a second registration boss attached to the top surface for extending upward into and engaging a second registration feature of the second wafer cassette,

wherein said first registration feature is incompatible with said second registration feature;

(c) a carriage supported by and movable in opposite directions along a track mechanism that is attached in fixed relationship to the support plate; and

(d) a first wafer pushing member rigidly connected to the carriage for engaging edges of semiconductor wafers in the first wafer cassette and pushing them out of the first wafer cassette into the second wafer cassette, and a second wafer pushing member rigidly connected to the carriage for engaging edges of semiconductor wafers in the second wafer cassette and pushing them out of the second wafer cassette into the first wafer cassette.

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Claim 4 (original): The wafer transfer machine of claim 3 including a handle attached to the carriage for manually moving carriage along the track mechanism to cause one of the first and second wafer pushing members to push wafers from one of the first and second wafer cassettes into the other.

Claim 5 (original): The wafer transfer machine of claim 3 wherein the support plate, carriage, and the first and second wafer pushing members are composed of plastic material.

Claim 6 (original): The wafer transfer machine of claim 3 wherein the track mechanism includes cylindrical first and second slide rods which are parallel to the top surface of the support plate and are parallel to each other.

Claim 7 (original): The wafer transfer machine of claim 6 wherein the carriage includes parallel first and second cylindrical holes through which the first and second slide rods, respectively, extend to allow bidirectional sliding of the carriage along the first and second slide rods.

Claim 8 (original): The wafer transfer machine of claim 3 wherein the track mechanism and carriage are underneath the support plate, and wherein the support plate includes a first elongated slot through which the first wafer pushing member extends upward to a level of wafers supported in the first wafer cassette, and wherein the support plate includes a second elongated slot through which the first wafer pushing member extends upward to a level of wafers supported in the second wafer cassette.

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Claim 9 (original): The wafer transfer machine of claim 8 wherein the first and second wafer pushing members are supported by opposite ends of a push-pull rod extending through the third cylindrical hole of the carriage and rigidly attached to the carriage.

Claim 10 (original): The wafer transfer machine of claim 9 wherein the first wafer pushing member includes a first vertical section having a lower end rigidly attached to a first end section of the push-pull rod, a first horizontal section having a first end attached to and integral with an upper end of the first vertical section and also having a second end attached to and integral with a lower end of a second vertical section, and wherein the second wafer pushing member includes a third vertical section having a lower end rigidly attached to a second end section of the push-pull rod, a second horizontal section having a first end attached to and integral with an upper end of the third vertical section and also having a second end attached to and integral with a lower end of a fourth vertical section.

Claim 11 (original): The wafer transfer machine of claim 4 including an alignment knob attached to an edge of the support plate in a location aligned with the handle when the carriage is located at a center position which allows placing and removal of the first and second wafer cassettes in engagement with the first and second registration bosses, respectively, and allows removal of the first and second wafer cassettes from the support plate.

Claim 12 (original): The wafer transfer machine of claim 8 including first, second, third, and fourth legs supporting first, second, third, and fourth corner portions of the support plate, respectively, wherein opposite ends of the first slide rod engage and are

supported by the first and fourth legs, respectively, and wherein opposite ends of the second slide rod engage and are supported by the second and third legs, respectively.

Claim 13 (cancelled)

Claim 14 (currently amended): A method of transferring wafers from either of a first wafer cassette and a second wafer cassette having incompatible registration features into the other wafer cassette, comprising:

(a) supporting the first wafer cassette on a support plate in registration with a first registration boss extending into and engaging a first registration feature of the first wafer cassette, and supporting the second wafer cassette on the support plate in registration with a second registration boss extending into and engaging a second registration feature of the second wafer cassette, one of the first and second wafer cassettes being loaded with semiconductor wafers and the other of the first and second wafer cassettes being empty;

wherein said first registration feature is incompatible with said second registration feature;

(b) supporting a first wafer pushing member and a second wafer pushing member by means of a carriage supported by and movable in opposite directions along a track mechanism; and

(c) moving the carriage in a direction that causes one of the first wafer pushing member and the second wafer pushing member which is closest to the semiconductor wafers in the loaded wafer cassette to engage the edges of the semiconductor wafers and push them out of the loaded wafer cassette into the empty wafer cassette.

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Claim 15 (original): The method of claim 14 further including moving the carriage to a centered position that allows removal of the first and second wafer cassettes from the support plate.

Claim 16 (cancelled)
